



Data Sheet
637.5MHz SAW 3030
SPT637M30E

V1.0

Features:

- Ceramic Package for Surface Mounted Technology (SMT)
- RoHS compatible
- Package size 3.00x3.00x1.25mm³
- Electrostatic Sensitive Device(ESD)

Specifications:

- Operation Temperature:-40°C to +85°C
- Compact miniature size
 - 3.0 mm × 3.0 mm footprint
 - 1.25 mm max-height

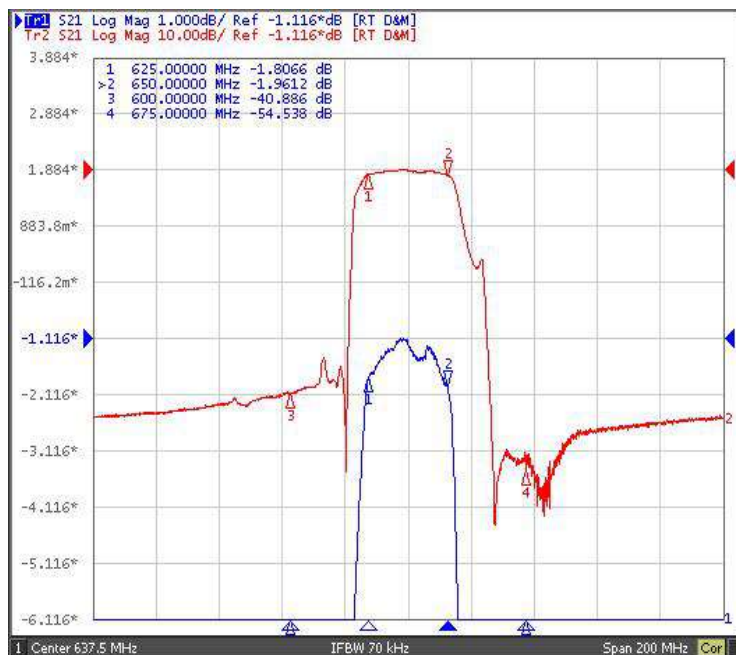
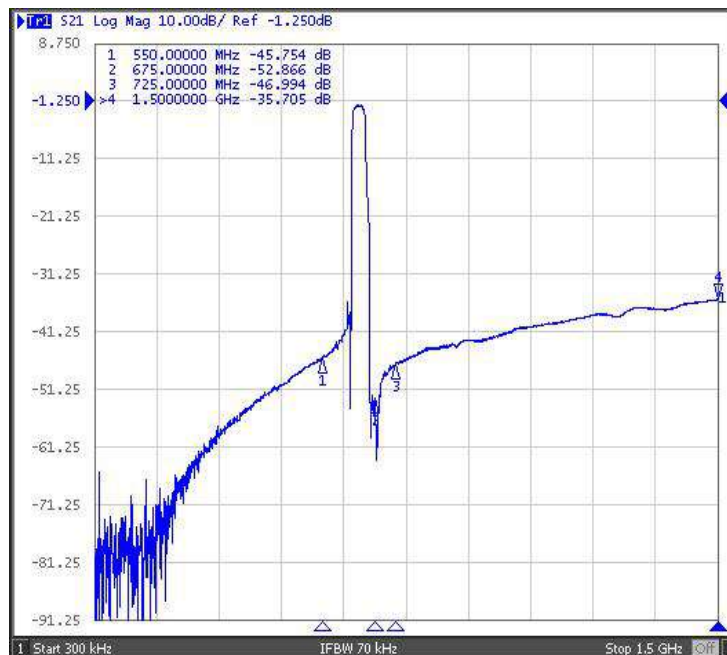
Applications:

- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 25.0 MHz

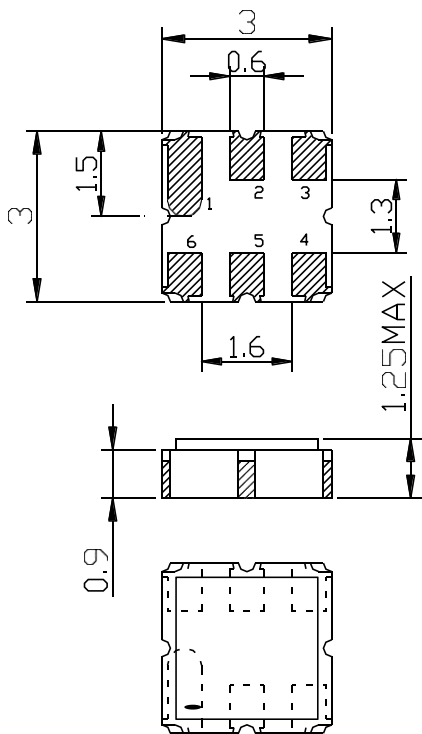
Electrical Specifications. Test Temperature: 25°C±2°C

Item		Minimum	Typical	Maximum	Unit
Center Frequency	fc		637.50		MHz
Insertion Loss(min)	IL		1.2	2.0	dB
Insertion Loss	625.00 -650.00 MHz		2.0	3.0	dB
Amplitude Ripple (p-p)	625.00 -650.00 MHz	$\Delta\alpha$	0.8*	1.0*	dB
Group Delay Ripple	625.00 -650.00 MHz		40.0	100.0	ns
Absolute Attenuation	α				
	DC- 550.00 MHz	40.0	45.0		dB
	550.00 - 600.00 MHz	35.0	38.0		dB
	675.00 - 725.00 MHz	40.0	45.0		dB
	725.00 - 1500.00 MHz	30.0	35.0		dB
Input VSWR	625.00 -650.00 MHz		1.6:1	2.0:1	
Output VSWR	625.00 -650.00 MHz		1.6:1	2.0:1	

“ * ” 为常温测试

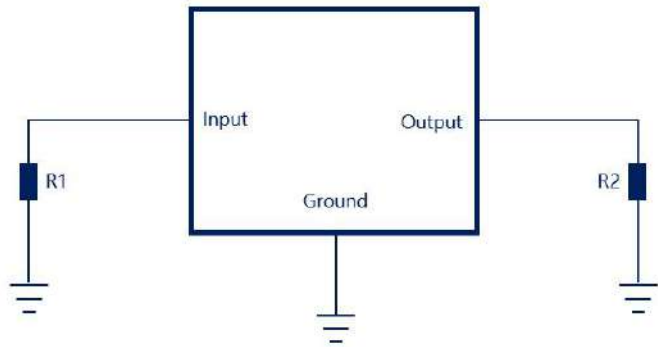
Frequency Characteristics.**Frequency Response****Frequency Response (wideband)**

Package & Dimensions



Pin No.	Description
2	Input
5	Output
1,3,4,6	Ground

Matching



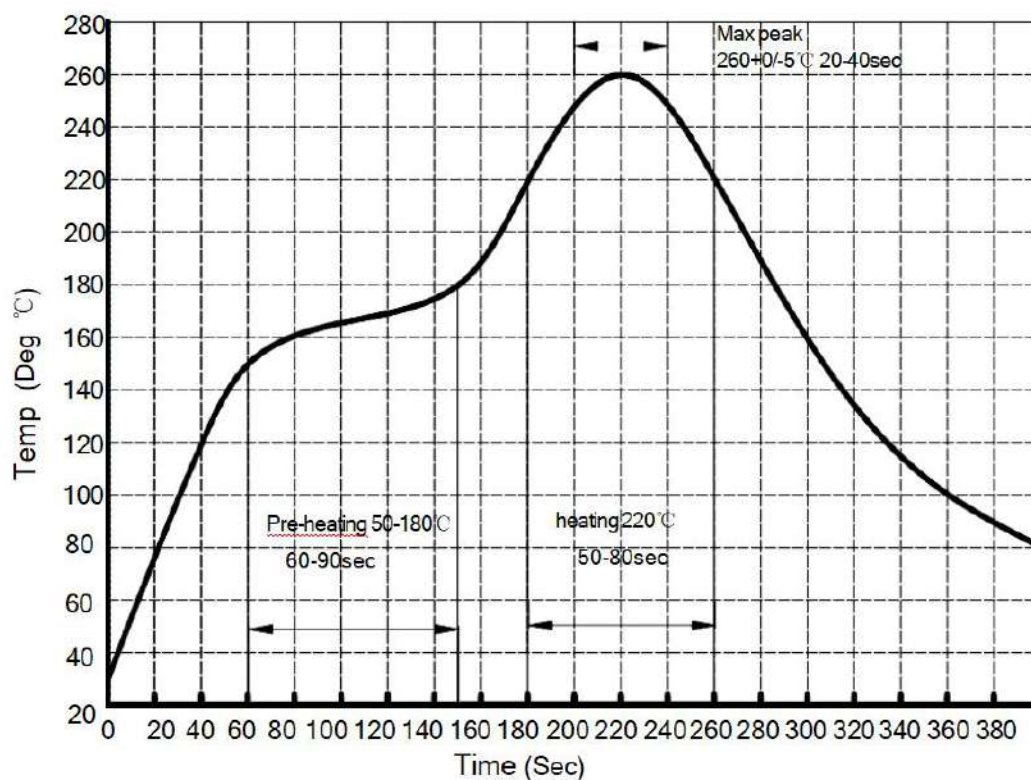
Port	Matching Component ¹
Input	R1: 50Ω
Output	R2: 50Ω

Matching component values shown are recommended based on the Spectron evaluation board. Value adjustment may be required on the end-user's circuit boards for the selected component manufacturer and PCB material.

Maximum Ratings

Item		Value	Unit
DC Voltage	V_{DC}	5	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	°C
RF Power Dissipation	P	20	dBm

Recommended Reflow Soldering Diagram



Ordering Information

Part Number	Number of Devices	Container
SPT637M30E	1000pcs	Tape and Reel

Reliability

No.	Test item	Test condition
1	Temperature Storage	Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h (2) Temperature: -55°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h
2	Humidity Test	Conditions: 60°C±2°C ,90~95% RH Duration: 250h
3	Thermal Shock	Heat cycle conditions: TA=-55°C±3°C, TB=85°C±2°C, t ₁ =t ₂ =30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.
4	Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude:1.5mm Directions: X,Y and Z Duration: 2h
5	Drop Test	Cycle time: 10 times Height: 1.0m
6	Solder Ability Test	Temperature: 245°C±5°C Duration: 3.0s--5.0s Depth: DIP--2/3 , SMD--1/5
7	Resistance to Soldering Heat	(1) Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration: 10±1s (2) Temperature of Soldering Iron: 350°C±10°C, Duration: 3~4s, Recovery time : 2 ± 0.5h

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